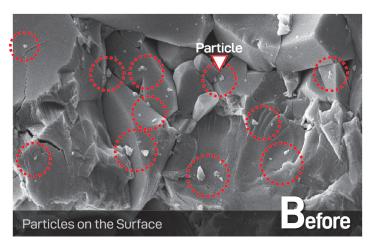


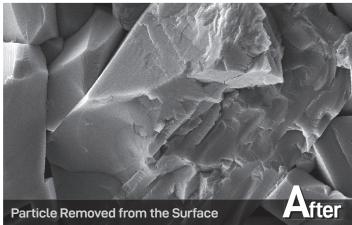
# **PSC**<sup>™</sup> Cleaning

As the primary physical reaction, fine CO<sub>2</sub> grains are sprayed at supersonic speed onto the object to be cleaned, leading to the occurrence of shrinkage cracks due to the impact and cooling of contamination,

and fine  $CO_2$  grains induce contamination ablation cleaning through sublimation as the secondary chemical reaction after penetrating in the generated crack. We have the technology that can selectively apply  $CO_2$  grain size according to the material and shape of contamination and objects to be cleaned, which can be very effective in preventing damage to the objects and cleaning weak points.

## Performance





# Method

- 1 Physical Blasting
  - Fine grains are sprayed with compressed air and collide with the surface.
- 2 Thermal Shock
  - Cracking Contaminants through Contracted by 78.5°C Sublimation Heat.
- 3 Sublimation Expansion
  - Expands to 800 times its own volume and destroys the interface.
- 4 Ablation
  - Contamination Removal by Compressed Air with High-Speed.

#### PSC™ Cleaning

# **Method Comparision**

| Method   | Secondary<br>Waste | Illuminance<br>Change | Substrate<br>Damage | Harmfulness |
|----------|--------------------|-----------------------|---------------------|-------------|
| PSC™     | X                  | X                     | X                   | X           |
| Water    | 0                  | Х                     | Х                   | 0           |
| Steam    | X                  | X                     | X                   | Χ           |
| Bead     | 0                  | 0                     | 0                   | 0           |
| Solvent  | 0                  | 0                     | 0                   | 0           |
| Chemical | 0                  | 0                     | 0                   | 0           |

When chemicals are used for cleaning, environmental pollution and changes, damage, and harm to the substrate are accompanied. Unlike chemicals, PSC™ Cleaning is a cleaning method that produces little secondary waste and does not cause changes in illuminance, damage to the substrate, or is not harmful.

### Merit





# **Application**

